

**DICING TAPE ATTACHING UNIT THAT CAN ATTACH PRE-CUT DICING TAPE  
AND GENERAL DICING TAPE TO WAFER AND IN-LINE SYSTEM  
HAVING THE DICING TAPE ATTACHING UNIT**

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Abstract of the Disclosure

A dicing tape attaching unit that can attach both a pre-cut dicing tape and a general dicing tape to a wafer in a semiconductor package assembling process, and an in-line system used in a semiconductor package process including the dicing tape attaching unit are provided. The dicing tape attaching unit supplies one of the pre-cut dicing tape and the general dicing tape and attaches it to a wafer according to the direction of rotation of a tape loader. Accordingly, without an additional pre-cut dicing tape attaching unit, either of the pre-cut dicing tape and the general dicing tape can be attached to the back side of the wafer by one and the same unit.

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